



# PSMN9R8-100YSF

NextPower 100 V, 9.7 mOhm N-channel MOSFET in LFAK56 package

25 January 2021

Objective data sheet

## 1. General description

NextPower 100 V, standard level gate drive MOSFET. Qualified to 175 °C and recommended for industrial and consumer applications.

## 2. Features and benefits

- Low  $Q_{rr}$  for higher efficiency and lower spiking
- Low  $Q_G \times R_{DS(on)}$  FOM for high efficiency switching applications
- Strong avalanche energy rating ( $E_{AS}$ )
- Avalanche rated and 100% tested
- Ha-free and RoHS compliant LFAK56 package
- Wave-solderable LFAK56 package

## 3. Applications

- Synchronous rectifier in AC-DC and DC-DC
- Primary side switch – 48 V DC-DC
- BLDC motor control
- USB-PD and mobile fast-charge adapters
- Flyback and resonant topologies

## 4. Quick reference data

Table 1. Quick reference data

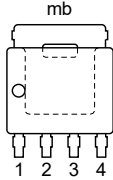
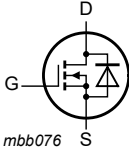
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{DS}$	drain-source voltage	$25\text{ °C} \leq T_j \leq 175\text{ °C}$	-	-	100	V
$I_D$	drain current	$V_{GS} = 10\text{ V}; T_{mb} = 25\text{ °C}$	-	-	61	A
$P_{tot}$	total power dissipation	$T_{mb} = 25\text{ °C}; \text{Fig. 1}$	-	-	147	W
$T_j$	junction temperature		-55	-	175	°C
<b>Static characteristics</b>						
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 10\text{ V}; I_D = 25\text{ A}; T_j = 25\text{ °C}$	-	7.3	9.7	mΩ
		$V_{GS} = 10\text{ V}; I_D = 25\text{ A}; T_j = 100\text{ °C}$	-	11.6	15.3	mΩ
<b>Dynamic characteristics</b>						
$Q_{GD}$	gate-drain charge	$I_D = 25\text{ A}; V_{DS} = 50\text{ V}; V_{GS} = 10\text{ V}$	[tbd]	6.9	[tbd]	nC
$Q_{G(tot)}$	total gate charge		[tbd]	34.6	[tbd]	nC
<b>Avalanche ruggedness</b>						
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	$I_D = 32.6\text{ A}; V_{sup} \leq 100\text{ V}; R_{GS} = 50\text{ Ω}; V_{GS} = 10\text{ V}; T_{j(init)} = 25\text{ °C}; \text{unclamped}$	[1]	-	107.8	mJ

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Source-drain diode</b>						
$Q_r$	recovered charge	$I_S = 25 \text{ A}$ ; $di_S/dt = -100 \text{ A}/\mu\text{s}$ ; $V_{GS} = 0 \text{ V}$ ; $V_{DS} = 50 \text{ V}$ ; $T_j = 25 \text{ }^\circ\text{C}$ ; <a href="#">Fig. 5</a>	-	30	-	nC

[1] Protected by 100% test

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source	 <p><b>LFAK56; Power-SO8 (SOT669)</b></p>	 <p>mbb076</p>
2	S	source		
3	S	source		
4	G	gate		
mb	D	mounting base; connected to drain		

## 6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PSMN9R8-100YSF	LFAK56; Power-SO8	plastic, single-ended surface-mounted package; 4 terminals	SOT669

## 7. Limiting values

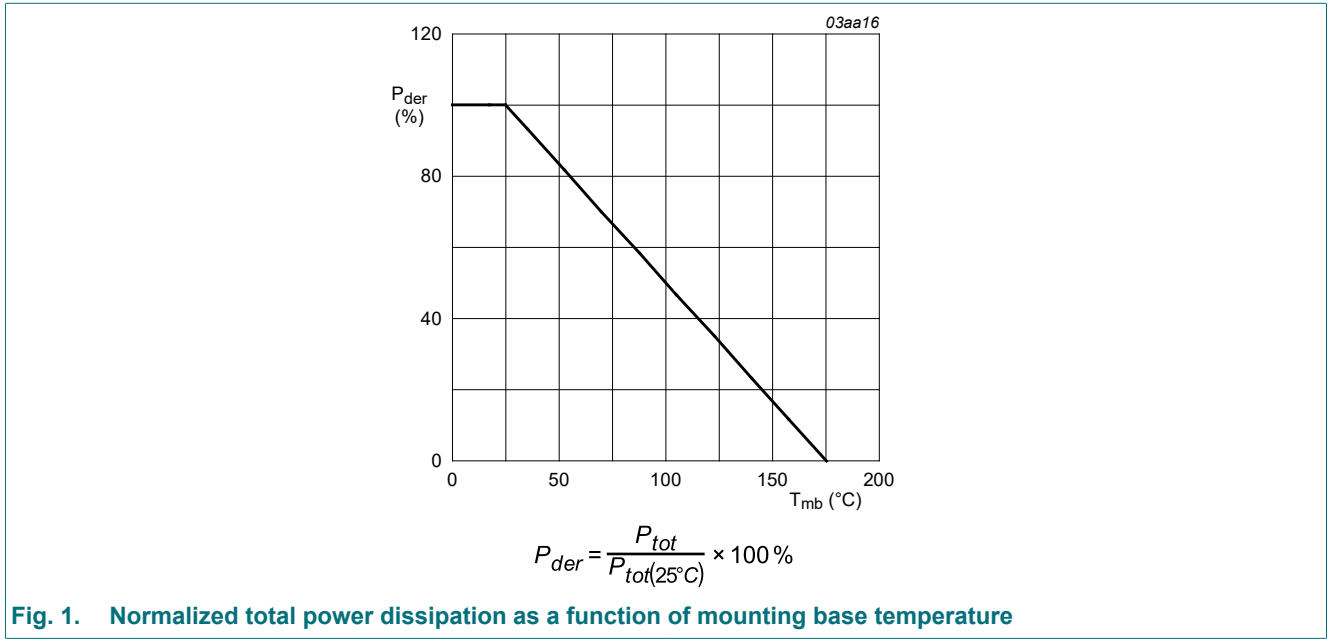
Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DS}$	drain-source voltage	$25 \text{ }^\circ\text{C} \leq T_j \leq 175 \text{ }^\circ\text{C}$	-	100	V
$V_{DGR}$	drain-gate voltage	$25 \text{ }^\circ\text{C} \leq T_j \leq 175 \text{ }^\circ\text{C}$ ; $R_{GS} = 20 \text{ k}\Omega$	-	100	V
$V_{GS}$	gate-source voltage		-20	20	V
$P_{tot}$	total power dissipation	$T_{mb} = 25 \text{ }^\circ\text{C}$ ; <a href="#">Fig. 1</a>	-	147	W
$I_D$	drain current	$V_{GS} = 10 \text{ V}$ ; $T_{mb} = 25 \text{ }^\circ\text{C}$	-	61	A
		$V_{GS} = 10 \text{ V}$ ; $T_{mb} = 100 \text{ }^\circ\text{C}$	-	43	A
$I_{DM}$	peak drain current	pulsed; $t_p \leq 10 \text{ } \mu\text{s}$ ; $T_{mb} = 25 \text{ }^\circ\text{C}$	-	244	A
$T_{stg}$	storage temperature		-55	175	$^\circ\text{C}$
$T_j$	junction temperature		-55	175	$^\circ\text{C}$
$T_{sld(M)}$	peak soldering temperature		-	260	$^\circ\text{C}$
<b>Source-drain diode</b>					
$I_S$	source current	$T_{mb} = 25 \text{ }^\circ\text{C}$	-	61	A
$I_{SM}$	peak source current	pulsed; $t_p \leq 10 \text{ } \mu\text{s}$ ; $T_{mb} = 25 \text{ }^\circ\text{C}$	-	244	A

Symbol	Parameter	Conditions		Min	Max	Unit
<b>Avalanche ruggedness</b>						
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	$I_D = 32.6 \text{ A}$ ; $V_{sup} \leq 100 \text{ V}$ ; $R_{GS} = 50 \Omega$ ; $V_{GS} = 10 \text{ V}$ ; $T_{j(\text{init})} = 25 \text{ }^\circ\text{C}$ ; unclamped	[1]	-	107.8	mJ
$I_{AS}$	non-repetitive avalanche current	$V_{sup} = 100 \text{ V}$ ; $V_{GS} = 10 \text{ V}$ ; $T_{j(\text{init})} = 25 \text{ }^\circ\text{C}$ ; $R_{GS} = 50 \Omega$	[1]	-	32.6	A

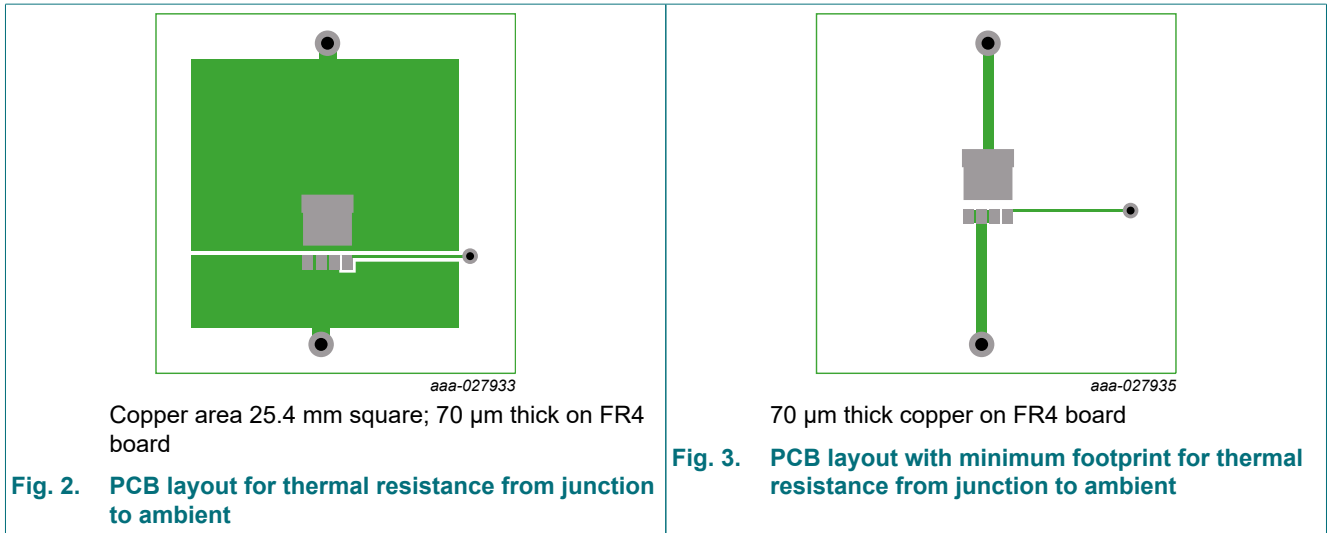
[1] Protected by 100% test



## 8. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base		-	[tbd]	1.02	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	<a href="#">Fig. 2</a>	-	42	-	K/W
		<a href="#">Fig. 3</a>	-	85	-	K/W

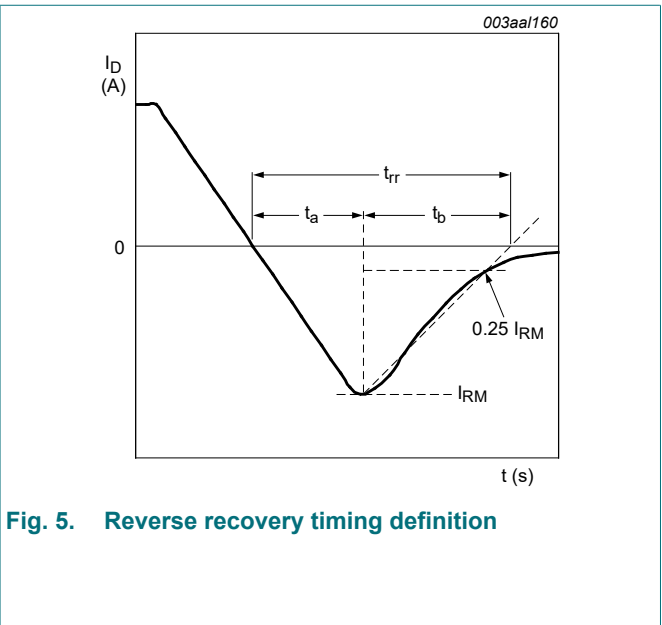
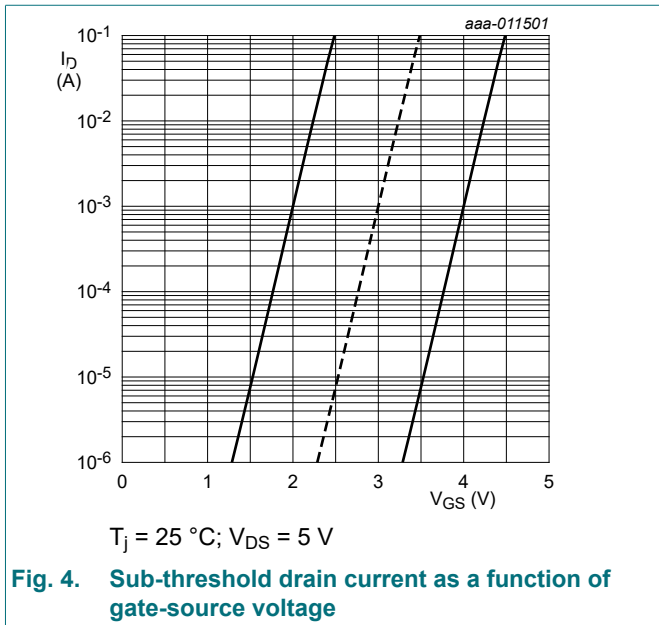


## 9. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 250 \mu A; V_{GS} = 0 V; T_j = 25 \text{ }^\circ C$	100	-	-	V
		$I_D = 250 \mu A; V_{GS} = 0 V; T_j = -55 \text{ }^\circ C$	90	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 1 \text{ mA}; V_{DS}=V_{GS}; T_j = 25 \text{ }^\circ C; \text{ Fig. 4}$	2	3	4	V
		$I_D = 1 \text{ mA}; V_{DS}=V_{GS}; T_j = 150 \text{ }^\circ C$	-	1.9	-	V
		$I_D = 1 \text{ mA}; V_{DS}=V_{GS}; T_j = -55 \text{ }^\circ C$	-	3.5	-	V
$\Delta V_{GS(th)}/\Delta T$	gate-source threshold voltage variation with temperature	$25 \text{ }^\circ C \leq T_j \leq 150 \text{ }^\circ C$	-	[tbd]	-	mV/K
$I_{DSS}$	drain leakage current	$V_{DS} = 100 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ }^\circ C$	-	[tbd]	25	$\mu A$
		$V_{DS} = 100 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 125 \text{ }^\circ C$	-	-	100	$\mu A$
$I_{GSS}$	gate leakage current	$V_{DS} = 20 \text{ V}; T_j = 25 \text{ }^\circ C$	-	2	100	nA
		$V_{DS} = -20 \text{ V}; T_j = 25 \text{ }^\circ C$	-	2	100	nA
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 10 \text{ V}; I_D = 25 \text{ A}; T_j = 25 \text{ }^\circ C$	-	7.3	9.7	m $\Omega$
		$V_{GS} = 7 \text{ V}; I_D = 25 \text{ A}; T_j = 25 \text{ }^\circ C$	-	8.8	11.4	m $\Omega$
		$V_{GS} = 10 \text{ V}; I_D = 25 \text{ A}; T_j = 100 \text{ }^\circ C$	-	11.6	15.3	m $\Omega$
		$V_{GS} = 10 \text{ V}; I_D = 25 \text{ A}; T_j = 175 \text{ }^\circ C$	-	16.6	22.2	m $\Omega$
$R_G$	gate resistance	$f = 1 \text{ MHz}; T_j = 25 \text{ }^\circ C$	[tbd]	1.6	[tbd]	$\Omega$
<b>Dynamic characteristics</b>						
$Q_{G(tot)}$	total gate charge	$I_D = 25 \text{ A}; V_{DS} = 50 \text{ V}; V_{GS} = 10 \text{ V}$	[tbd]	34.6	[tbd]	nC
		$I_D = 0 \text{ A}; V_{DS} = 0 \text{ V}; V_{GS} = 10 \text{ V}$	-	18	-	nC
$Q_{GS}$	gate-source charge	$I_D = 25 \text{ A}; V_{DS} = 50 \text{ V}; V_{GS} = 10 \text{ V}$	[tbd]	10	[tbd]	nC
$Q_{GS(th)}$	pre-threshold gate-source charge		-	6.6	-	nC
$Q_{GS(th-pl)}$	post-threshold gate-source charge		-	3.4	-	nC
$Q_{GD}$	gate-drain charge		[tbd]	6.9	[tbd]	nC

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{GS(pl)}$	gate-source plateau voltage	$V_{DS} = 50\text{ V}$	-	4.5	-	V
$C_{iss}$	input capacitance	$V_{DS} = 50\text{ V}; V_{GS} = 0\text{ V}; f = 1\text{ MHz}; T_j = 25\text{ }^\circ\text{C}$	[tbd]	2422	[tbd]	pF
$C_{oss}$	output capacitance		[tbd]	531	[tbd]	pF
$C_{rss}$	reverse transfer capacitance		[tbd]	16	[tbd]	pF
$t_{d(on)}$	turn-on delay time	$V_{DS} = 50\text{ V}; R_L = 2\text{ }\Omega; V_{GS} = 10\text{ V}; R_{G(ext)} = 5\text{ }\Omega$	-	8.7	-	ns
$t_r$	rise time		-	7.4	-	ns
$t_{d(off)}$	turn-off delay time		-	20.9	-	ns
$t_f$	fall time		-	10.5	-	ns
<b>Source-drain diode</b>						
$V_{SD}$	source-drain voltage	$I_S = 25\text{ A}; V_{GS} = 0\text{ V}; T_j = 25\text{ }^\circ\text{C}$	-	-	1.2	V
$t_{rr}$	reverse recovery time	$I_S = 25\text{ A}; di_S/dt = -100\text{ A}/\mu\text{s}; V_{GS} = 0\text{ V}; V_{DS} = 50\text{ V}; \text{Fig. 5}$	-	35	-	ns
$Q_r$	recovered charge	$I_S = 25\text{ A}; di_S/dt = -100\text{ A}/\mu\text{s}; V_{GS} = 0\text{ V}; V_{DS} = 50\text{ V}; T_j = 25\text{ }^\circ\text{C}; \text{Fig. 5}$	-	30	-	nC



10. Package outline

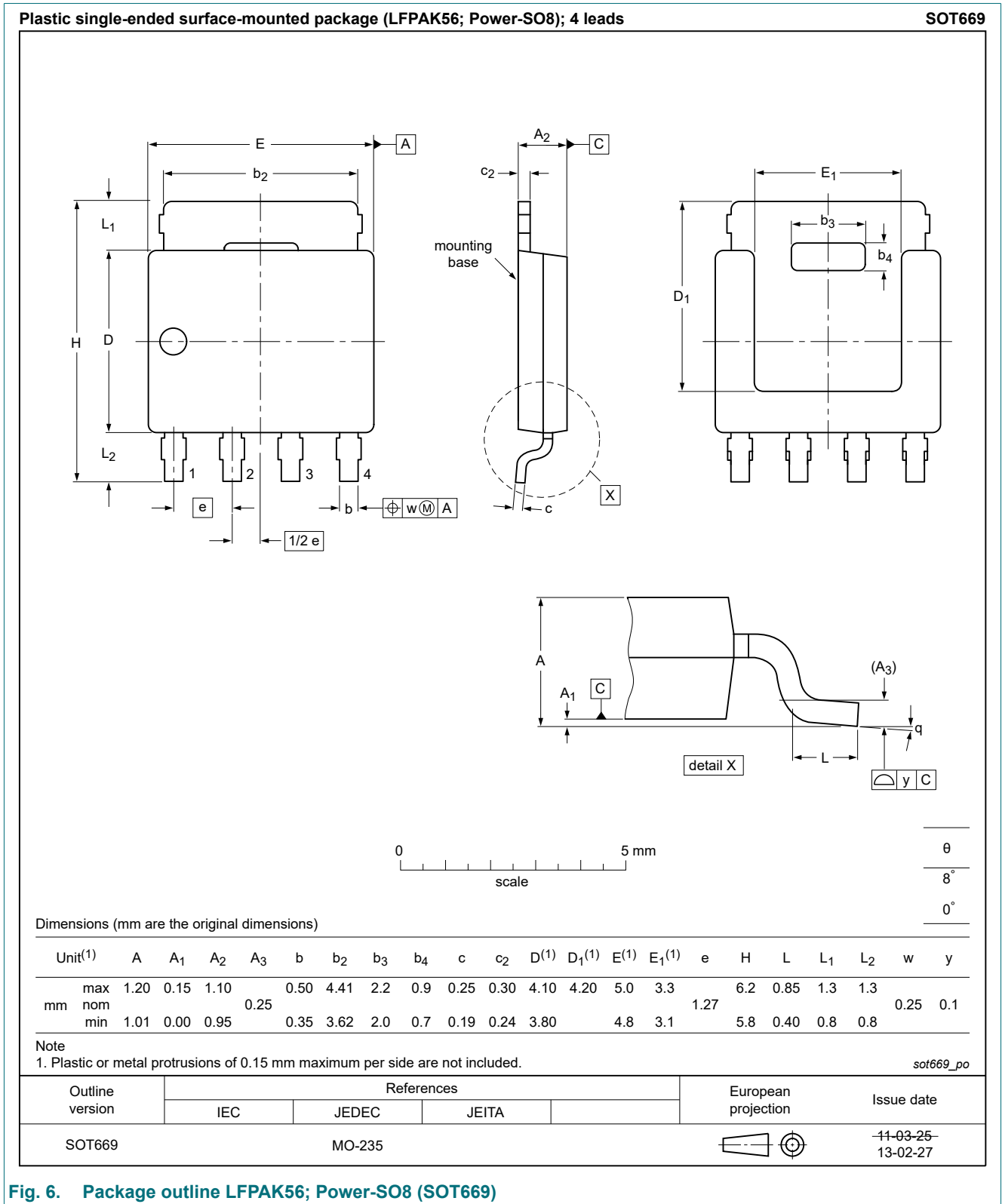


Fig. 6. Package outline LPAK56; Power-SO8 (SOT669)

### 11. Soldering

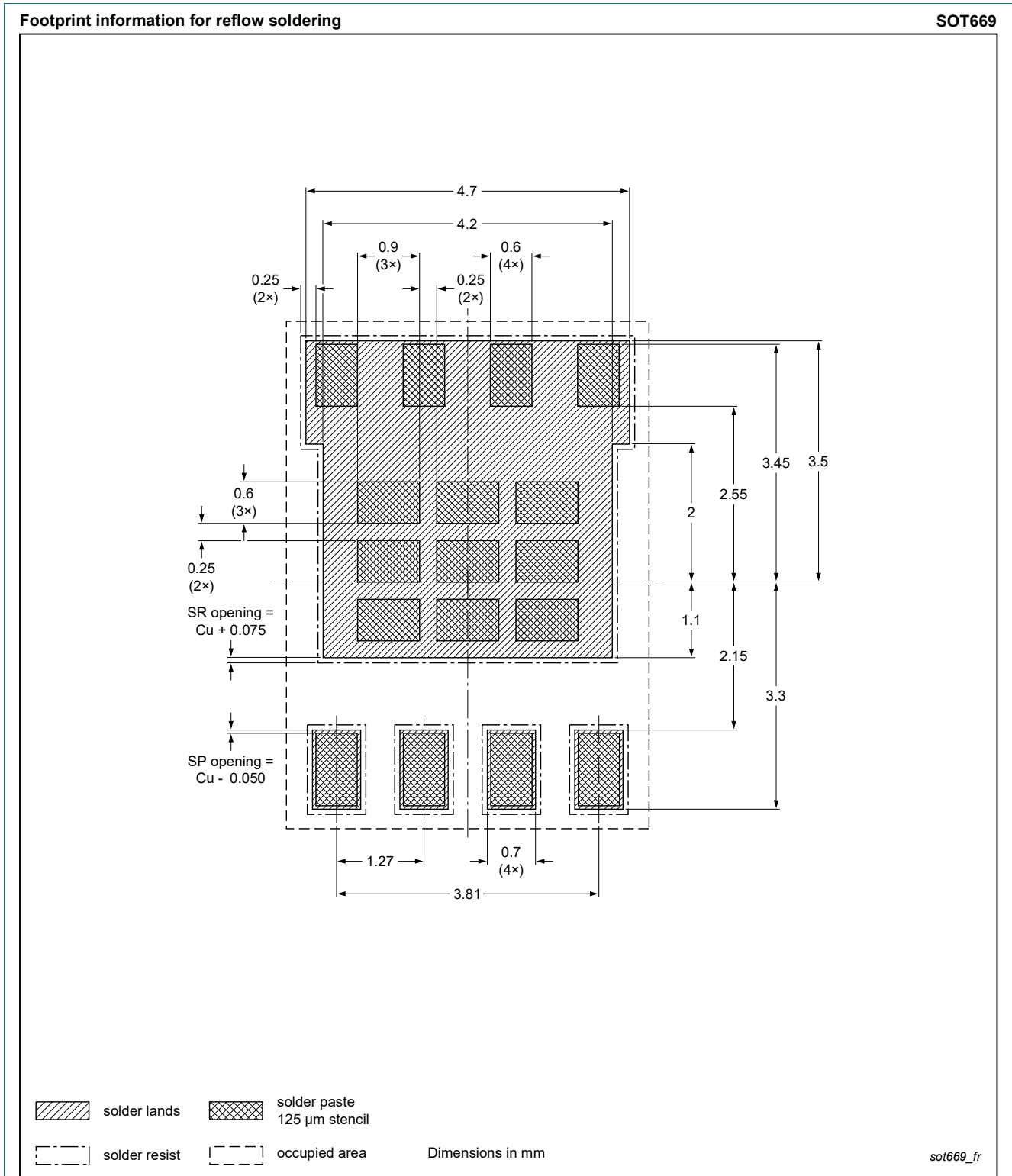
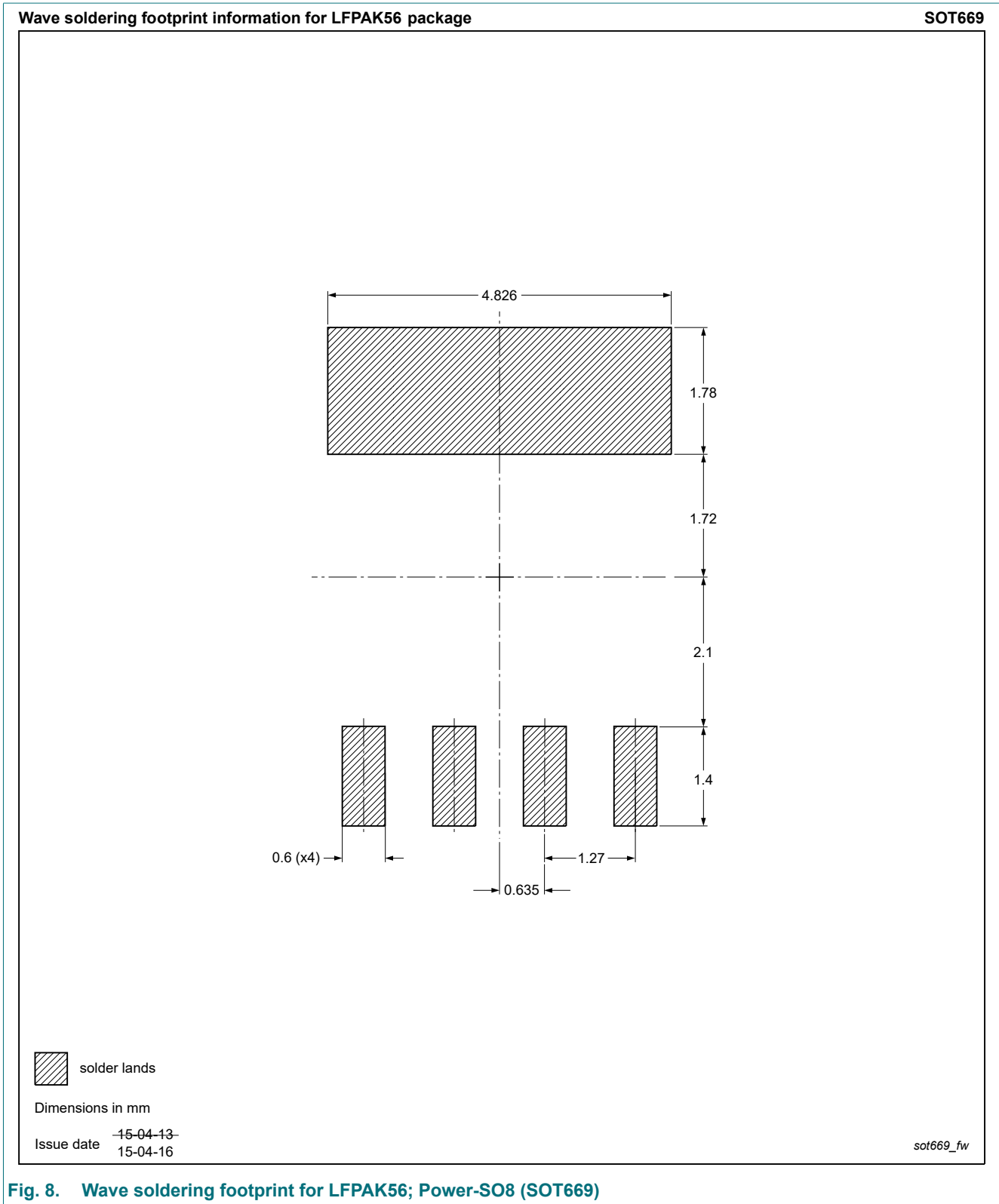


Fig. 7. Reflow soldering footprint for LPAK56; Power-SO8 (SOT669)





## 12. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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